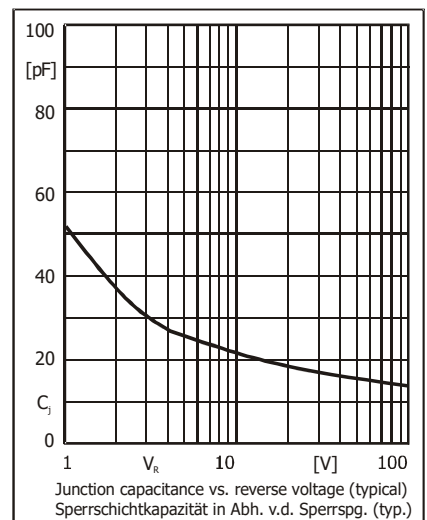
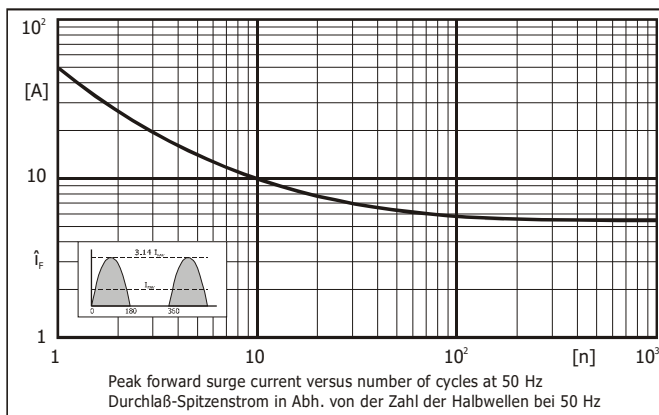
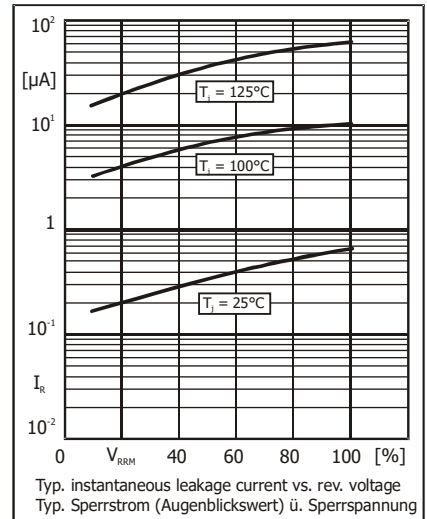
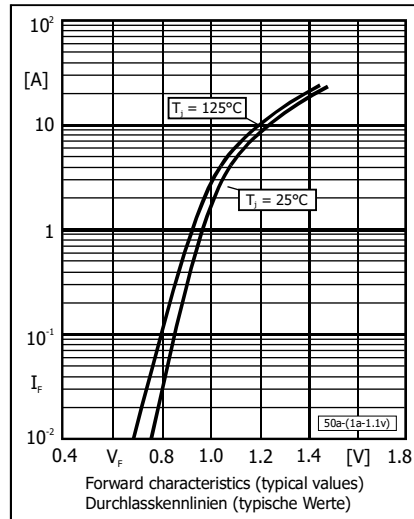
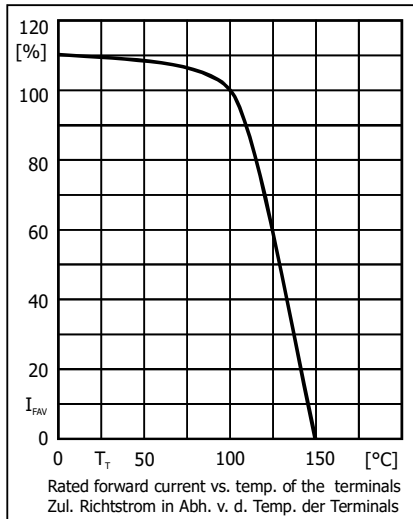




**Characteristics**

**Kennwerte**

Forward voltage – Durchlass-Spannung	$T_j = 25^\circ\text{C}$	$I_F = 2 \text{ A}$	$V_F$	< 1.15
Leakage current Sperrstrom	$T_j = 25^\circ\text{C}$ $T_j = 100^\circ\text{C}$	$V_R = V_{RRM}$	$I_R$	< 5 $\mu\text{A}$ < 100 $\mu\text{A}$
Reverse recovery time – Sperrverzug	$I_F = 0.5 \text{ A}$ through/über $I_R = 1 \text{ A}$ to $I_R = 0.25 \text{ A}$			$t_{rr}$ typ. 1500 ns
Thermal resistance junction-ambient – Wärmewiderstand Sperrschicht-Umgebung				$R_{thA}$ < 50 K/W <sup>1)</sup>
Thermal resistance junction-terminal – Wärmewiderstand Sperrschicht-Anschluss				$R_{thT}$ < 15 K/W



Disclaimer: See data book page 2 or [website](#)  
Haftungsausschluss: Siehe Datenbuch Seite 2 oder [Internet](#)

1 Mounted on P.C. board with 50 mm<sup>2</sup> copper pads at each terminal  
Montage auf Leiterplatte mit 50 mm<sup>2</sup> Kupferpad je Anschluss